

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-13 (canceled).

Claim 14 (original): A cavity-type integrated circuit package comprising:
a premolded package body;
a plurality of leads, each lead extending from an interior of said package body to an exterior thereof;
a first semiconductor die mounted to a first side of a die attach pad, in a first cavity of said package body;
a first plurality of wire bonds connecting various ones of said leads and said first semiconductor die;
a first fill material substantially filling said first cavity of said package body;
a second semiconductor die mounted to a second side of said die attach pad in said package body;
a second plurality of wire bonds connecting various ones of said leads and said second semiconductor die;
a second fill material covering a portion of said plurality of leads; and
a lid for enclosing said second semiconductor die and said second plurality of wire bonds in said package body.

Claim 15 (original): The cavity-type integrated circuit package according to claim 14, wherein said first fill material is the same as said second fill material.